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(54) **A mounting arrangement for lighting modules and corresponding method**

(57) A lighting module (10) includes a base plate (102) for fixing to a mounting surface (100), and a reflector body (106) carrying a printed circuit board (107) with one or more electrical light sources (L) such as high power LEDs. The printed circuit board (107) includes electrical contact pins to the electrical light sources (L). The base plate (102) and the reflector body (106) are provided with complementary coupling formations (1024, 1068; 1025, 1070) for snap-like coupling the base plate (102) and the reflector body (106) with an electrical line (104) interposed therebetween for feeding the light sources (L) with the electrical contact pins (108) electrically contacting the electrical line (104). The module (10) may include force-generating formations (1072) to urge the printed circuit board (107) against the base plate (102) to promote heat transfer therebetween.

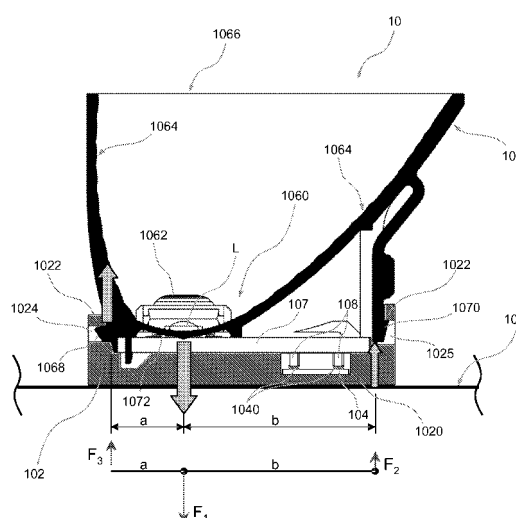


Fig. 4